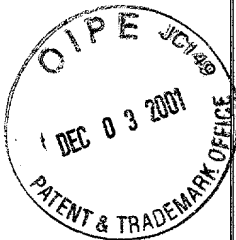


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicants: Lee John Smith, David Albert Zoba
Assignee: Amkor Technology, Inc.
Title: Thin Semiconductor Package Including Stacked Dies
Serial No.: 09/944,732 Filing Date: August 31, 2001
Examiner: Unknown Group Art Unit: Unknown
Docket No.: M-11443 US

San Francisco, California
December 3, 2001

Attn: Customer Service Center
Initial Patent Examination Division
U.S. Patent and Trademark Office
P.O. Box 2327
Washington, D.C. 20231

RESPONSE TO NOTICE TO FILE CORRECTED APPLICATION PAPERS-
FILING DATE GRANTED

Dear Sir:

In response to the "Notice to File Corrected Application Papers- Filing Date Granted" mailed by the United States Patent and Trademark Office on October 5, 2001, the following documents are enclosed:

1. 4 (Four) Sheets of Formal Drawings, consisting of Figs. 1, 2, 3, 3A, 4, 4A, 5, 6, 7, 8, and 9; and
2. Copy of Notice to File Corrected Application Papers- Filing Date Granted.

The Commissioner is hereby authorized to charge any additional fees, which may be required, or credit any overpayment to Deposit Account No. 19-2386.

LAW OFFICES OF
SKJERVEN MORRILL
MacPHERSON LLP

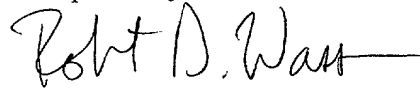
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It is hereby respectfully submitted that the enclosed documents overcome the noted application informality. Please telephone the undersigned at (415) 217-6000, if there are any questions. This form is being submitted in duplicate.

EXPRESS MAIL LABEL NO:

EL 873 331 583 US

Respectfully submitted,



Robert D. Wasson
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